

PNM523T201E0-VB Datasheet

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY

| V_{DS} (V) | $R_{DS(on)}$ (Ω) | I_D (A) ^c | Q_g (TYP.) |
|--------------|---------------------------|------------------------|--------------|
| 20 | 0.270 at $V_{GS} = 4.5$ V | 0.85 | 1.4 nC |
| | 0.390 at $V_{GS} = 2.5$ V | 0.70 | |

FEATURES

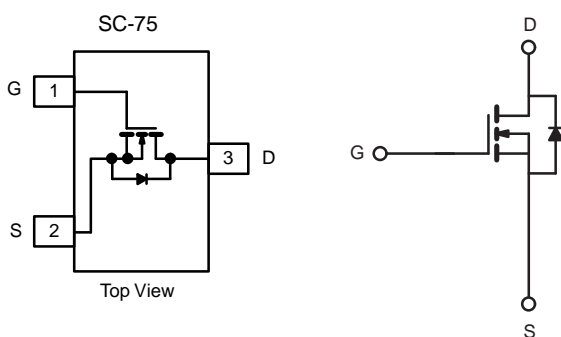
- Trench power MOSFET
- 100 % R_g tested

APPLICATIONS

- Smart phones, tablet PC's
 - DC/DC converters
 - Boost converters
 - Load switch, OVP switch



RoHS
COMPLIANT
HALOGEN
FREE



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise noted)

| PARAMETER | | SYMBOL | LIMIT | UNIT |
|--|--------------------------|----------------|---------------------|------------------|
| Drain-Source Voltage | | V_{DS} | 20 | V |
| Gate-Source Voltage | | V_{GS} | ± 12 | |
| Continuous Drain Current ($T_J = 150^\circ\text{C}$) | $T_C = 25^\circ\text{C}$ | I_D | 0.85 | A |
| | $T_C = 70^\circ\text{C}$ | | 0.65 | |
| | $T_A = 25^\circ\text{C}$ | | 0.7 ^{a, b} | |
| | $T_A = 70^\circ\text{C}$ | | 0.6 ^{a, b} | |
| Pulsed Drain Current ($t = 300 \mu\text{s}$) | | I_{DM} | 6 | |
| Continuous Source-Drain Diode Current | $T_C = 25^\circ\text{C}$ | I_S | 0.4 | |
| | $T_A = 25^\circ\text{C}$ | | 0.3 | |
| Maximum Power Dissipation | $T_C = 25^\circ\text{C}$ | P_D | 0.5 | W |
| | $T_C = 70^\circ\text{C}$ | | 0.3 | |
| | $T_A = 25^\circ\text{C}$ | | 0.4 ^{a, b} | |
| | $T_A = 70^\circ\text{C}$ | | 0.3 ^{a, b} | |
| Operating Junction and Storage Temperature Range | | T_J, T_{stg} | -55 to +150 | $^\circ\text{C}$ |
| Soldering Recommendations (Peak Temperature) | | | 260 | |

THERMAL RESISTANCE RATINGS

| PARAMETER | | SYMBOL | TYP. | MAX. | UNIT |
|---|---------------|------------|------|------|--------------------|
| Maximum Junction-to-Ambient ^{a, d} | $t \leq 10$ s | R_{thJA} | 250 | 300 | $^\circ\text{C/W}$ |
| Maximum Junction-to-Foot (Drain) | Steady State | R_{thJF} | 225 | 270 | |

Notes

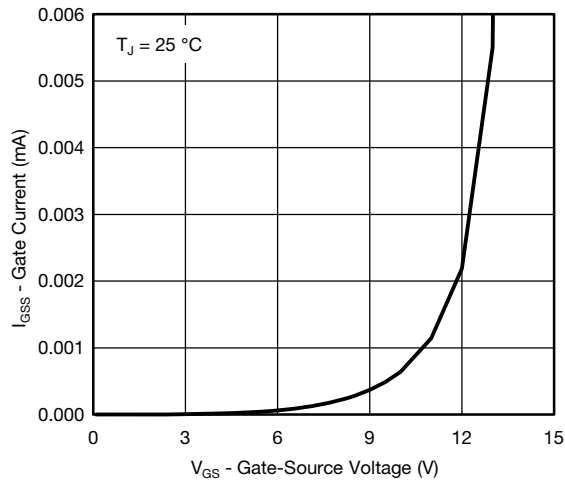
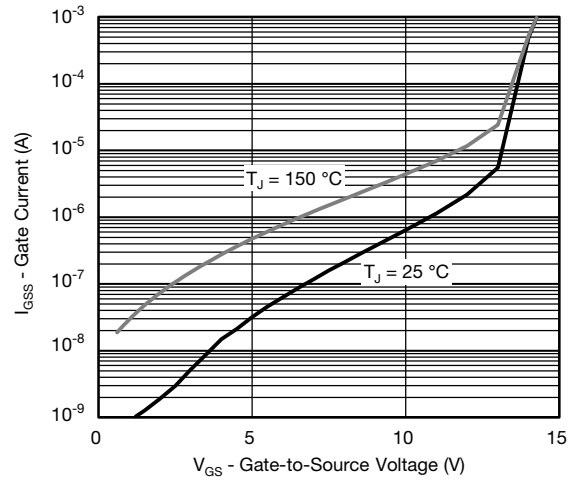
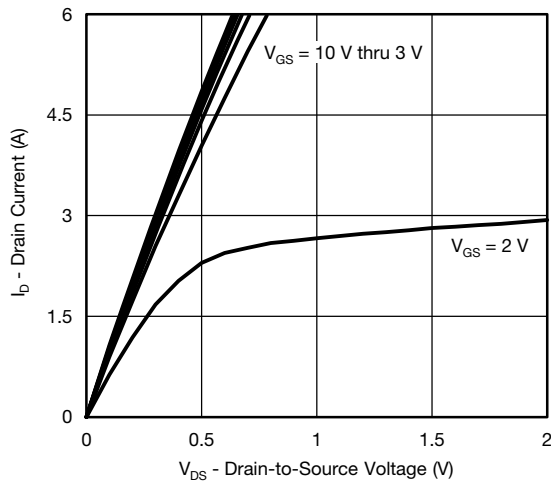
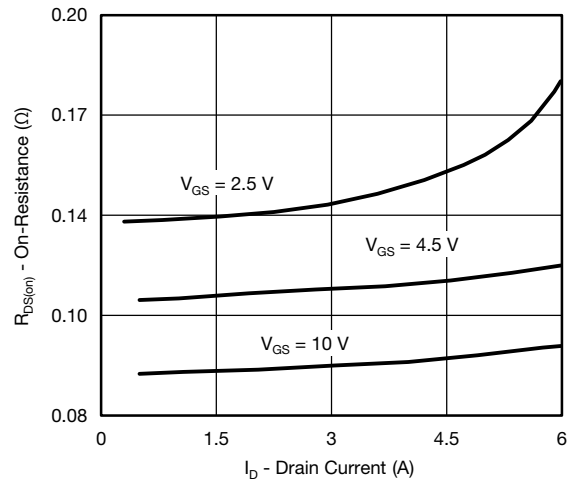
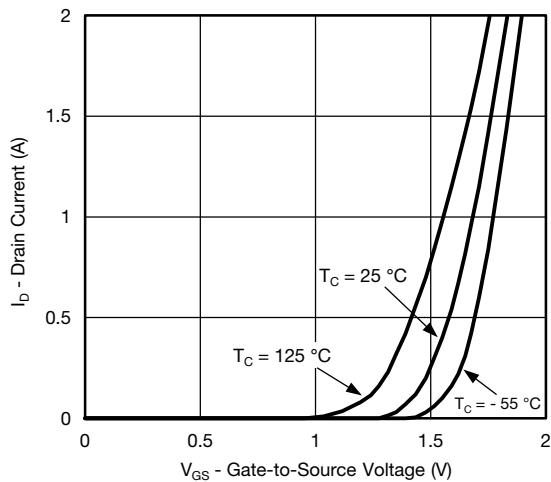
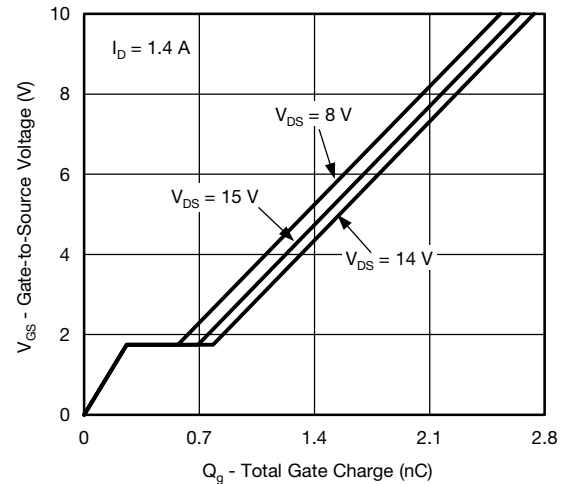
- Surface mounted on 1" x 1" FR4 board.
- $t = 10$ s.
- Based on $T_C = 25^\circ\text{C}$.
- Maximum under steady state conditions is 360°C/W .

| SPECIFICATIONS (T _J = 25 °C, unless otherwise noted) | | | | | | |
|---|--------------------------------------|---|------|-------|------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | 20 | - | - | V |
| V _{DS} Temperature Coefficient | ΔV _{DS} /T _J | I _D = 250 μA | - | 32 | - | mV/°C |
| V _{GS(th)} Temperature Coefficient | ΔV _{GS(th)} /T _J | | - | -3 | - | |
| Gate-Source Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | 0.5 | - | 1.0 | V |
| Gate-Source Leakage | I _{GSS} | V _{DS} = 0 V, V _{GS} = 4.5 V | - | - | 0.1 | μA |
| | | V _{DS} = 0 V, V _{GS} = ± 12 V | - | - | ± 20 | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 20 V, V _{GS} = 0 V | - | - | 0.1 | |
| | | V _{DS} = 20 V, V _{GS} = 0 V, T _J = 55 °C | - | - | 10 | |
| On-State Drain Current ^a | I _{D(on)} | V _{DS} ≥ 5 V, V _{GS} = 10 V | 2 | - | - | A |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = 4.5 V, I _D = 1 A | - | 0.270 | - | Ω |
| | | V _{GS} = 2.5 V, I _D = 0.5 A | - | 0.390 | - | |
| Forward Transconductance ^a | g _{fs} | V _{DS} = 10 V, I _D = 1.4 A | - | 5 | - | S |
| Dynamic ^b | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz | - | 105 | - | pF |
| Output Capacitance | C _{oss} | | - | 23 | - | |
| Reverse Transfer Capacitance | C _{rss} | | - | 11 | - | |
| Total Gate Charge | Q _g | V _{DS} = 15 V, V _{GS} = 10 V, I _D = 1.4 A | - | 2.7 | 4.1 | nC |
| | | V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 1.4 A | - | 1.4 | 2.1 | |
| Gate-Source Charge | Q _{gs} | | - | 0.3 | - | |
| Gate-Drain Charge | Q _{gd} | | - | 0.5 | - | |
| Gate Resistance | R _g | f = 1 MHz | 1.4 | 7 | 14 | Ω |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = 15 V, R _L = 13.6 Ω I _D ≅ 1.1 A, V _{GEN} = 10 V, R _g = 1 Ω | - | 2 | 4 | ns |
| Rise Time | t _r | | - | 9 | 18 | |
| Turn-Off Delay Time | t _{d(off)} | | - | 8 | 16 | |
| Fall Time | t _f | | - | 8 | 16 | |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = 15 V, R _L = 13.6 Ω I _D ≅ 1.1 A, V _{GEN} = 4.5 V, R _g = 1 Ω | - | 8 | 16 | |
| Rise Time | t _r | | - | 13 | 20 | |
| Turn-Off Delay Time | t _{d(off)} | | - | 15 | 23 | |
| Fall Time | t _f | | - | 6 | 12 | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | - | - | 0.4 | A |
| Pulse Diode Forward Current ^a | I _{SM} | | - | - | 6 | |
| Body Diode Voltage | V _{SD} | I _F = 1.1 A | - | 0.8 | 1.2 | V |
| Body Diode Reverse Recovery Time | t _{rr} | I _F = 1.1 A, dI/dt = 100 A/μs, T _J = 25 °C | - | 8 | 16 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | | - | 3 | 6 | nC |
| Reverse Recovery Fall Time | t _a | | - | 5 | - | ns |
| Reverse Recovery Rise Time | t _b | | - | 3 | - | |

Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
 b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Gate Source Voltage vs. Gate Current

Gate Source Voltage vs. Gate Current

Output Characteristics

On-Resistance vs. Drain Current

Transfer Characteristics

Gate Charge

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



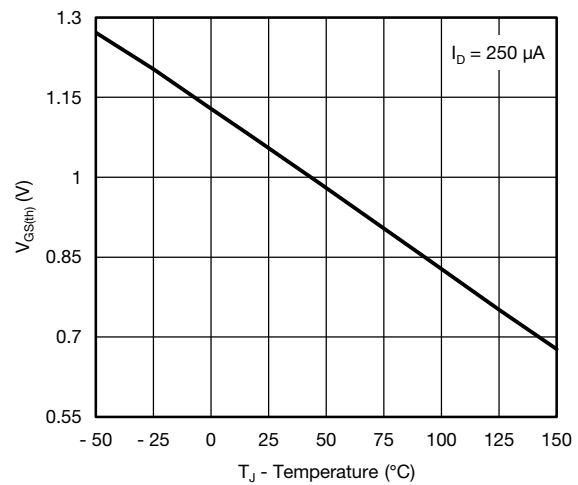
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



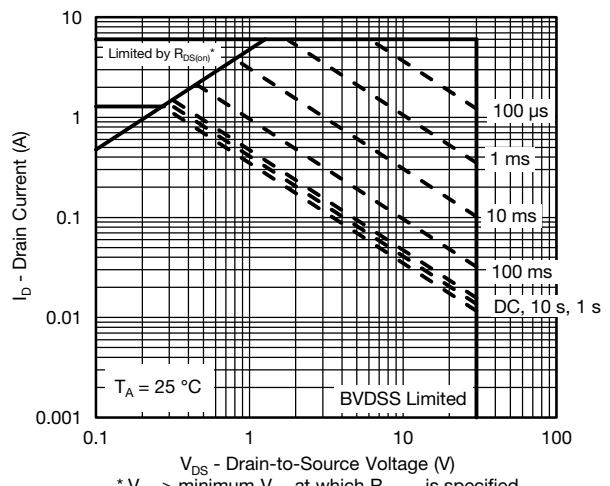
On-Resistance vs. Gate-to-Source Voltage



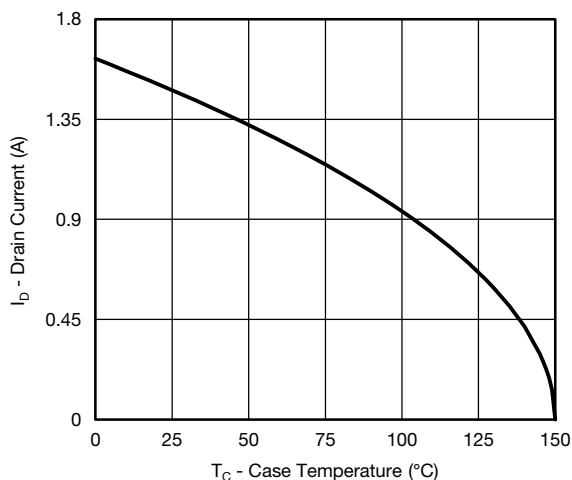
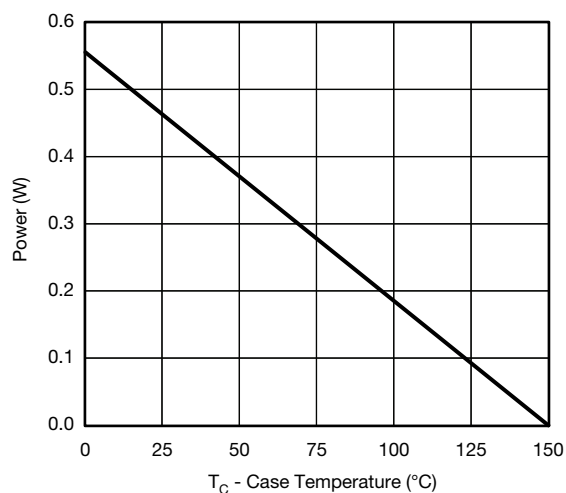
Threshold Voltage



Single Pulse Power, Junction-to-Ambient



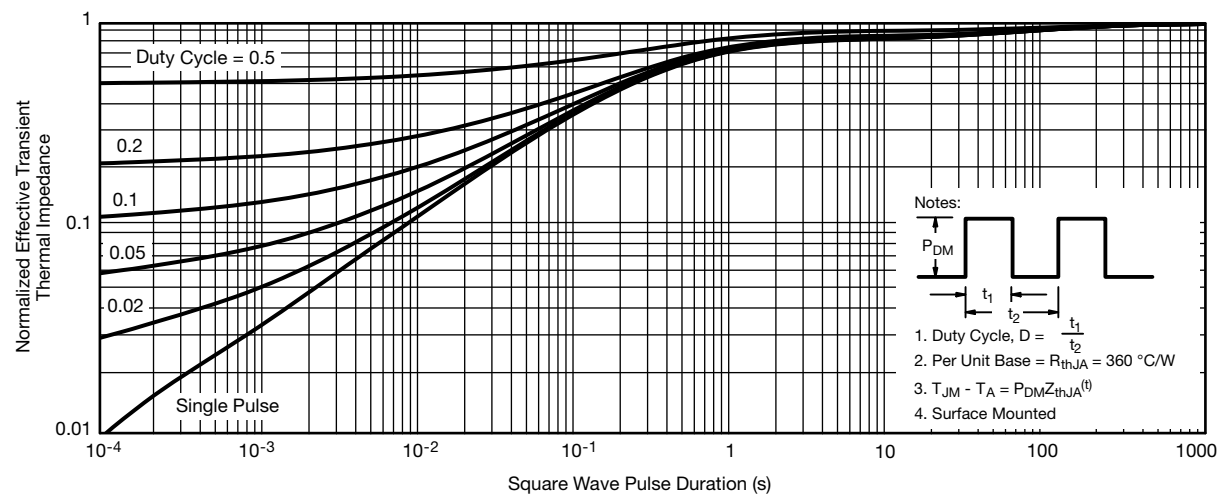
Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Current Derating*

Power, Junction-to-Case

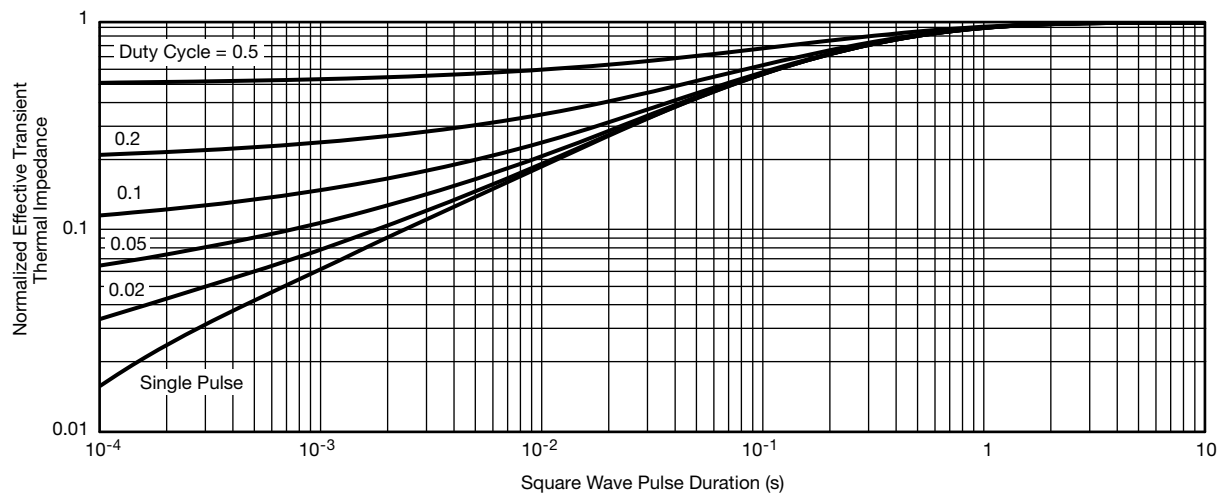
Power, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

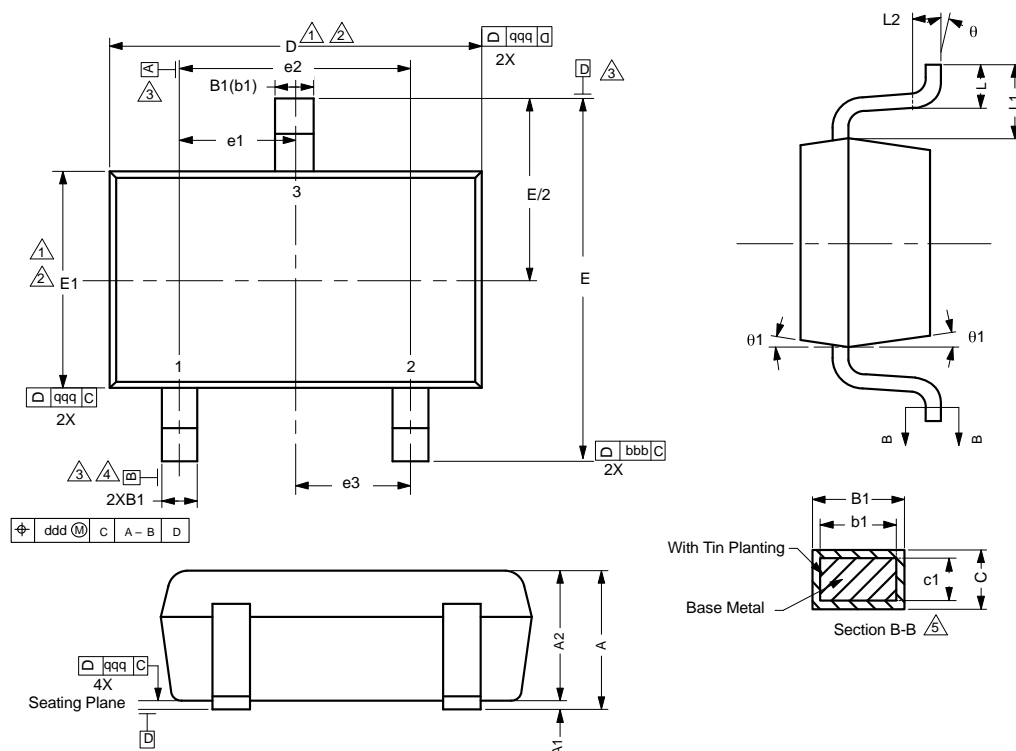


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

SC-75A: 3 Leads



Notes

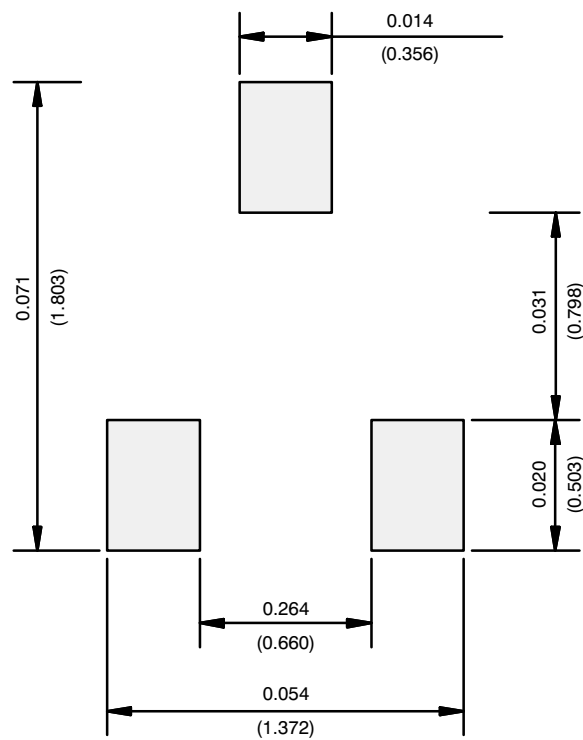
Dimensions in millimeters will govern.

1. Dimension D does not include mold flash, protrusions or gate burrs. Mold flash protrusions or gate burrs shall not exceed 0.10 mm per end. Dimension E1 does not include Interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.10 mm per side.
2. Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.
3. Datums A, B and D to be determined 0.10 mm from the lead tip.
4. Terminal positions are shown for reference only.
5. These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

| DIMENSIONS | TOLERANCES |
|------------|------------|
| aaa | 0.10 |
| bbb | 0.10 |
| ccc | 0.10 |
| ddd | 0.10 |

| DIM. | MILLIMETERS | | | NOTE |
|----------------|-------------|-------|------|------|
| | MIN. | NOM. | MAX. | |
| A | - | - | 0.80 | |
| A ₁ | 0.00 | - | 0.10 | |
| A ₂ | 0.65 | 0.70 | 0.80 | |
| B ₁ | 0.19 | - | 0.24 | 5 |
| b ₁ | 0.17 | - | 0.21 | |
| c | 0.13 | - | 0.15 | 5 |
| c ₁ | 0.10 | - | 0.12 | 5 |
| D | 1.48 | 1.575 | 1.68 | 1, 2 |
| E | 1.50 | 1.60 | 1.70 | |
| E ₁ | 0.66 | 0.76 | 0.86 | 1, 2 |
| e ₁ | 0.50 BSC | | | |
| e ₂ | 1.00 BSC | | | |
| e ₃ | 0.50 BSC | | | |
| L | 0.15 | 0.205 | 0.30 | |
| L ₁ | 0.40 ref. | | | |
| L ₂ | 0.15 BSC | | | |
| θ | 0° | - | 8° | |
| θ ₁ | 4° | - | 10° | |

RECOMMENDED MINIMUM PADS FOR SC-75A: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

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